

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Matsumura, et al.
 Appl. No. : 10/678,855
 Filed : October 3, 2003
 For : DICING/DIE-BONDING FILM,
 METHOD OF FIXING CHIPPED
 WORK AND SEMICONDUCTOR
 DEVICE
 Examiner : Laura M Schillinger
 Group Art Unit : 2813

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

October 12, 2005

(Date)

[Signature]
 Katsuhiro Arai, Reg. No. 43,315

*AMS B
 entered
 11/12/05
 11/15/05
 11/21/05*

AMENDMENT AFTER FINAL

Mail Stop AF

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed June 14, 2005, please reconsider the present application in light of the following amendments and comments.

Summary of Interview begins on page 2 of this paper.

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 15 of this paper.

Remarks/Arguments begin on page 17 of this paper.